

# Specification of Automotive MLCC

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL21C101JB61PNC**
- Description : **CAP, 100pF, 50V, ±5%, COG, 0805**
- AEC-Q 200 Specified

## A. Samsung Part Number

**CL**   **21**   **C**   **101**   **J**   **B**   **6**   **1**   **P**   **N**   **C**  
 ①   ②   ③   ④   ⑤   ⑥   ⑦   ⑧   ⑨   ⑩   ⑪

|                         |                                       |  |                   |                         |  |    |               |  |  |  |
|-------------------------|---------------------------------------|--|-------------------|-------------------------|--|----|---------------|--|--|--|
| ① Series                | Samsung Multi-layer Ceramic Capacitor |  |                   |                         |  |    |               |  |  |  |
| ② Size                  | 0805 (inch code)                      |  | L:                | 2.0 ± 0.1 mm            |  | W: | 1.25 ± 0.1 mm |  |  |  |
| ③ Dielectric            | C0G                                   |  | ⑧ Inner electrode | Ni                      |  |    |               |  |  |  |
| ④ Capacitance           | 100 pF                                |  | Termination       | Cu                      |  |    |               |  |  |  |
| ⑤ Capacitance tolerance | ±5 %                                  |  | Plating           | Sn 100% (Pb Free)       |  |    |               |  |  |  |
| ⑥ Rated Voltage         | 50 V                                  |  | ⑨ Product         | Automotive              |  |    |               |  |  |  |
| ⑦ Thickness             | 0.6 ± 0.1 mm                          |  | ⑩ Grade code      | Standard                |  |    |               |  |  |  |
|                         |                                       |  | ⑪ Packaging       | Cardboard Type, 7" reel |  |    |               |  |  |  |

## B. Reliability Test and Judgement condition

|                                        | Performance                                                                                                                                                                                        | Test condition                                                                                                                                                                 |
|----------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>High Temperature Exposure</b>       | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±2.5% or ±0.25pF whichever is larger<br>Q : 1000 min<br>IR : More than 10,000MΩ or 500MΩ×μF<br>Whichever is Smaller | Unpowered, 1000hrs@T=150 °C<br>Measurement at 24±2hrs after test conclusion                                                                                                    |
| <b>Temperature Cycling</b>             | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±2.5% or ±0.25pF whichever is larger<br>Q : 1000 min<br>IR : More than 10,000MΩ or 500MΩ×μF<br>Whichever is Smaller | 1000Cycles<br>Measurement at 24±2hrs after test conclusion<br>1 cycle condition :<br>-55+0/-3 °C (15±3min) -> Room Temp(1min.)<br>-> 125+3/-0 °C (15±3min) -> Room Temp(1min.) |
| <b>Destructive Physical Analysis</b>   | No Defects or abnormalities                                                                                                                                                                        | Per EIA 469                                                                                                                                                                    |
| <b>Moisture Resistance</b>             | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±2.5% or ±0.25pF whichever is larger<br>Q : 350 min<br>IR : More than 10,000MΩ or 500MΩ×μF<br>Whichever is Smaller  | 10Cycles, t=24hrs/cycle<br>Heat (25~65 °C) and humidity (80~98%), Unpowered<br>measurement at 24±2hrs after test conclusion                                                    |
| <b>Humidity Bias</b>                   | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±2.5% or ±0.25pF whichever is larger<br>Q : 200 min<br>IR : More than 500MΩ or 25MΩ×μF<br>Whichever is Smaller      | 1000hrs 85 °C/85%RH, Rated Voltate and 1.3~1.5V,<br>Add 100kohm resistor<br>Measurement at 24±2hrs after test conclusion<br>The charge/discharge current is less than 50mA.    |
| <b>High Temperature Operating Life</b> | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±3.0% or ±0.3pF whichever is larger<br>Q : 350 min<br>IR : More than 10,000MΩ or 500MΩ×μF<br>Whichever is Smaller   | 1000hrs @ TA=125 °C, 200% Rated Voltage,<br>Measurement at 24±2hrs after test conclusion<br>The charge/discharge current is less than 50mA.                                    |

|                             | Performance                                                                                                                                                                                                    | Test condition                                                                                                                                                                                                                                                                               |           |  |  |           |          |      |          |        |       |           |           |
|-----------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------|--|--|-----------|----------|------|----------|--------|-------|-----------|-----------|
| External Visual             | No abnormal exterior appearance                                                                                                                                                                                | Microscope (´10)                                                                                                                                                                                                                                                                             |           |  |  |           |          |      |          |        |       |           |           |
| Physical Dimensions         | Within the specified dimensions                                                                                                                                                                                | Using The calipers                                                                                                                                                                                                                                                                           |           |  |  |           |          |      |          |        |       |           |           |
| Mechanical Shock            | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±2.5% or ±0.25pF whichever is larger<br>Q, IR : initial spec.                                                                   | Three shocks in each direction should be applied along<br>3 mutually perpendicular axes of the test specimen (18 shocks) <table><tr><td>Peakvalue</td><td>Duration</td><td>Wave</td><td>Velocity</td></tr><tr><td>1,500G</td><td>0.5ms</td><td>Half sine</td><td>4.7m/sec.</td></tr></table> |           |  |  | Peakvalue | Duration | Wave | Velocity | 1,500G | 0.5ms | Half sine | 4.7m/sec. |
| Peakvalue                   | Duration                                                                                                                                                                                                       | Wave                                                                                                                                                                                                                                                                                         | Velocity  |  |  |           |          |      |          |        |       |           |           |
| 1,500G                      | 0.5ms                                                                                                                                                                                                          | Half sine                                                                                                                                                                                                                                                                                    | 4.7m/sec. |  |  |           |          |      |          |        |       |           |           |
| Vibration                   | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±2.5% or ±0.25pF whichever is larger<br>Q, IR : initial spec.                                                                   | 5g's for 20min., 12cycles each of 3 orientations,<br>Use 8"×5" PCB 0.031" Thick 7 secure points on one long side<br>and 2 secure points at corners of opposite sides. Parts mounted<br>within 2" from any secure point. Test from 10~2000Hz .                                                |           |  |  |           |          |      |          |        |       |           |           |
| Resistance to Solder Heat   | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±2.5% or ±0.25pF whichever is larger<br>Q, IR : initial spec.                                                                   | Solder pot : 260±5 °C, 10±1sec.                                                                                                                                                                                                                                                              |           |  |  |           |          |      |          |        |       |           |           |
| Thermal Shock               | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±2.5% or ±0.25pF whichever is larger<br>Q, IR : initial spec.                                                                   | -55 °C/+125 °C .<br>Note: Number of cycles required-300,<br>Maximum transfer time-20 sec, Dwell time-15min. Air-Air                                                                                                                                                                          |           |  |  |           |          |      |          |        |       |           |           |
| ESD                         | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±2.5% or ±0.25pF whichever is larger<br>Q, IR : initial spec.                                                                   | AEC-Q200-002                                                                                                                                                                                                                                                                                 |           |  |  |           |          |      |          |        |       |           |           |
| Solderability               | 95% of the terminations is to be soldered<br>evenly and continuously                                                                                                                                           | a) Preheat at 155 °C for 4 hours, Immerse in solder for 5s at 245±5 °C<br>b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 °C<br>c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 °C<br>solder : a solution ethanol and rosin                                    |           |  |  |           |          |      |          |        |       |           |           |
| Electrical Characterization | Capacitance : Within specified tolerance<br>Q :     1000     max.<br>IR(25 °C) : More than 100,000MΩ or 1,000MΩ×μF<br>IR(125 °C) : More than10,000MΩ or 100MΩ×μF<br>Whichver is Smaller<br>Dielectric Strength | The Capacitance /Q should be measured at 25 °C ,<br>1MHz±10%, 0.5~5Vrms<br>I.R. should be measured with a DC voltage not exceeding<br>Rated Voltage @25 °C, @125 °C for 60~120 sec.<br>Dielectric Strength : 250% of the rated voltage for 1~5 seconds                                       |           |  |  |           |          |      |          |        |       |           |           |
| Board Flex                  | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±5.0% or ±0.5pF whichever is larger                                                                                             | Bending to the limit (3mm) for 5 seconds                                                                                                                                                                                                                                                     |           |  |  |           |          |      |          |        |       |           |           |
| Terminal Strength(SMD)      | Appearance : No abnormal exterior appearance<br>Capacitance Change :<br>within ±2.5% or ±0.25pF whichever is larger                                                                                            | 18N, for 60±1 sec.                                                                                                                                                                                                                                                                           |           |  |  |           |          |      |          |        |       |           |           |
| Beam Load                   | Destruction value should not be exceed<br>Chip Length < 2.5mm<br>a) Chip Thickness > 0.5mm : 20N<br>b) Chip Thickness ≤ 0.5mm : 8N                                                                             | Beam speed<br>0.5±0.05mm/sec                                                                                                                                                                                                                                                                 |           |  |  |           |          |      |          |        |       |           |           |
| Temperature Characterisitcs | C0G<br>(From -55 °C to 125 °C, Capacitance change should be within ±30PPM/°C)                                                                                                                                  |                                                                                                                                                                                                                                                                                              |           |  |  |           |          |      |          |        |       |           |           |

### C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max )  
Meet IPC/JEDEC J-STD-020 D Standard

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.



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- Защита от снятия компонента с производства.



#### Как с нами связаться

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